Basic information

2018/2947(DEA) DEA - Delegated acts procedure	Procedure completed - delegated act enters into force
Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages Supplementing 2008/0240(COD) **Subject** 3.40.06 Electronics, electrotechnical industries, ICT, robotics 3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)	

Key players

	Committee responsible	Rapporteur	Appointed
European Parliament	ENVI Environment, Public Health and Food Safety		

Key events

Date	Event	Reference	Summary
16/11/2018	Non-legislative basic document published	C(2018)07499	
16/11/2018	Initial period for examining delegated act 2 month(s)		
28/11/2018	Committee referral announced in Parliament		
24/01/2019	Delegated act not objected by Parliament		

Technical information

Procedure reference	2018/2947(DEA)
Procedure type	DEA - Delegated acts procedure
Procedure subtype	Examination of delegated act
Amendments and repeals	Supplementing 2008/0240(COD)
Stage reached in procedure	Procedure completed - delegated act enters into force
Committee dossier	ENVI/8/15029

Documentation gateway

European Commission

Document type	Reference	Date	Summary

Non-legislative basic document	C(2018)07499	16/11/2018	
Document attached to the procedure	C(2025)5889	25/08/2025	

Additional information

Source	Document	Date
European Commission	EUR-Lex	